



Material Content Data Sheet



Sales Product Name				BGSX 212MA18 E6327		Issued		23. January 2018	
MA#				MA001479316					
Package				PG-ATSLP-18-2		Weight*		6.41 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.223	3.49	3.49	34872	34872	
bumps	non noble metal	copper	7440-50-8	0.025	0.39	0.39	3897	3897	
encapsulation	organic material	carbon black	1333-86-4	0.023	0.36		3644		
	plastics	epoxy resin	-	0.677	10.57		105681		
leadfinish	inorganic material	silicondioxide	60676-86-0	3.969	61.97	72.90	619509	728834	
	noble metal	gold	7440-57-5	0.059	0.92		9214		
	non noble metal	nickel	7440-02-0	0.067	1.05	1.97	10508	19722	
substrate	organic material	carbon black	1333-86-4	0.002	0.03		309		
	plastics	epoxy resin	-	0.077	1.20		12050		
	non noble metal	copper	7440-50-8	0.505	7.88		78842		
ubm	inorganic material	silicondioxide	60676-86-0	0.581	9.06	18.17	90631	181832	
	non noble metal	copper	7440-50-8	0.002	0.03		266		
	non noble metal	titanium	7440-32-6	0.001	0.01		94		
	non noble metal	tungsten	7440-33-7	0.000	0.00	0.04	49	409	
solder	noble metal	silver	7440-22-4	0.000	0.00		33		
	non noble metal	tin	7440-31-5	0.009	0.14	0.14	1396	1429	
solder resists	inorganic material	bariumsulfate	7727-43-7	0.040	0.62		6236		
	inorganic material	silicondioxide	60676-86-0	0.039	0.62		6164		
*deviation	plastics	acrylic resin	-	0.106	1.66	2.90	16605	29005	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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